

April 2000

FQB9N50 / FQI9N50

500V N-Channel MOSFET

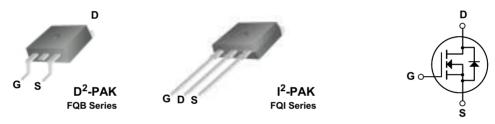
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.

Features

- 9.0A, 500V, $R_{DS(on)}$ = 0.73 Ω @V_{GS} = 10 V Low gate charge (typical 28 nC)
- Low Crss (typical 20 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB9N50 / FQI9N50	Units
V _{DSS}	Drain-Source Voltage		500	V
I _D	Drain Current - Continuous (T _C = 25°C	:)	9.0	Α
	- Continuous (T _C = 100°	C)	5.7	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	36	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	360	mJ
I _{AR}	Avalanche Current	(Note 1)	9.0	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	14.7	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		3.13	W
	Power Dissipation (T _C = 25°C)		147	W
	- Derate above 25°C		1.18	W/°C
T_J , T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C
			300	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.85	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	racteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced	to 25°C		0.55		V/°C
I _{DSS}	Zana Osta Walter a Basis O and	V _{DS} = 500 V, V _{GS} = 0 V				1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 400 V, T _C = 125°C				10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V				-100	nA
	racteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 4.5 A			0.58	0.73	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 4.5 A	(Note 4)		8.2		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			1100 160 20	1450 210 30	pF pF
	ng Characteristics				20	30	рг
t _{d(on)}	Turn-On Delay Time	V 050 V I 0 0 A			25	60	ns
t _r	Turn-On Rise Time	$V_{DD} = 250 \text{ V}, I_{D} = 9.0 \text{ A},$ $R_{G} = 25 \Omega$			95	200	ns
t _{d(off)}	Turn-Off Delay Time	NG - 23 22			55	120	ns
t _f	Turn-Off Fall Time	-	(Note 4, 5)		60	130	ns
Qg	Total Gate Charge	V _{DS} = 400 V, I _D = 9.0 A,			28	36	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V			7.0		nC
Q _{gd}	Gate-Drain Charge	(Note 4,			12.5		nC
Drain-S	ource Diode Characteristics a	nd Maximum Ratings	5			-	
I _S	Maximum Continuous Drain-Source Diode Forward Current					9.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current				36	Α
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 9.0 \text{ A}$				1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 9.0 \text{ A},$			300		ns
		dl _F / dt = 100 A/μs	(Note 4)				μC

- Notes:
 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 8mH, $I_{AS} = 9.0A$, $V_{DD} = 50V$, $R_{G} = 25 \Omega$, Starting $T_{J} = 25^{\circ}C$ 3. $I_{gD} \leq 9.0A$, $d/Idt \geq 200A/\mu_{S}$, $V_{DD} \leq BV_{DSS}$, Starting $T_{J} = 25^{\circ}C$ 4. Pulse Test: Pulse width $\leq 300\mu_{S}$, Duty cycle $\leq 2\%$ 5. Essentially independent of operating temperature

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Typical Characteristics

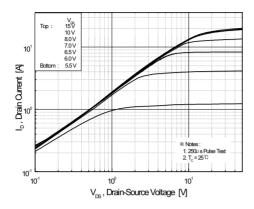


Figure 1. On-Region Characteristics

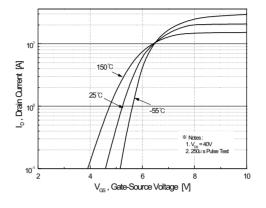


Figure 2. Transfer Characteristics

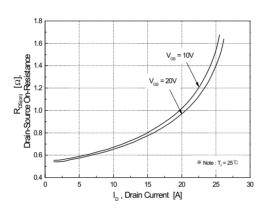


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

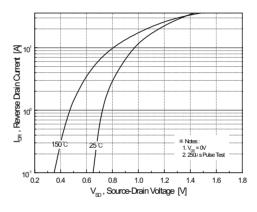


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

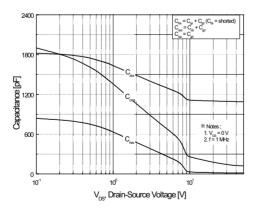


Figure 5. Capacitance Characteristics

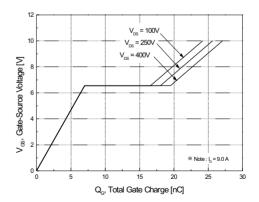
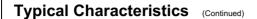
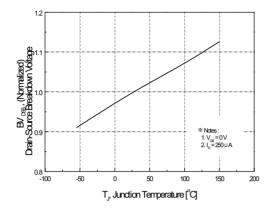


Figure 6. Gate Charge Characteristics





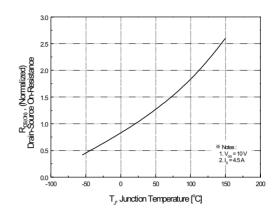
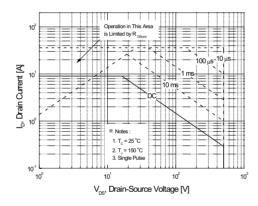


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



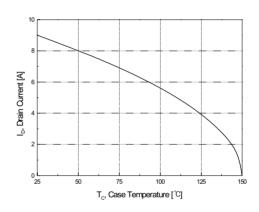


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

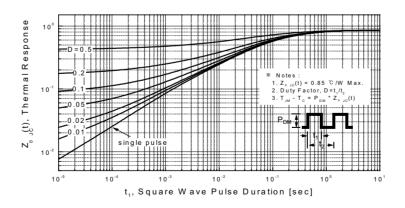
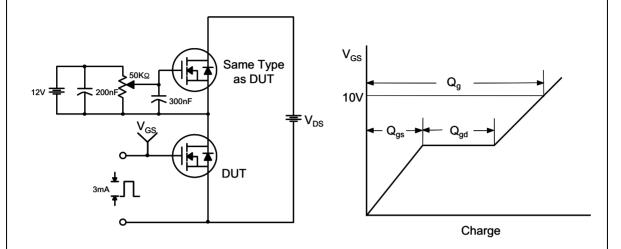


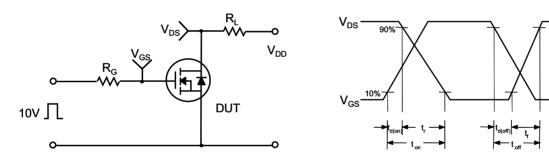
Figure 11. Transient Thermal Response Curve

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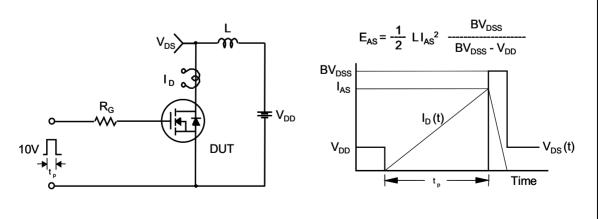
Gate Charge Test Circuit & Waveform



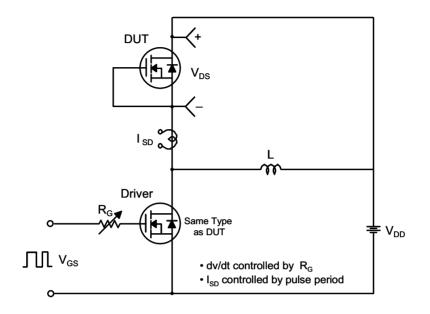
Resistive Switching Test Circuit & Waveforms

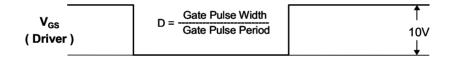


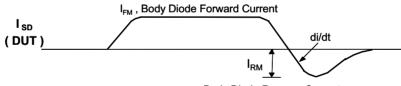
Unclamped Inductive Switching Test Circuit & Waveforms



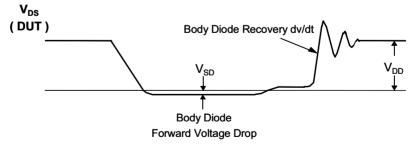
Peak Diode Recovery dv/dt Test Circuit & Waveforms



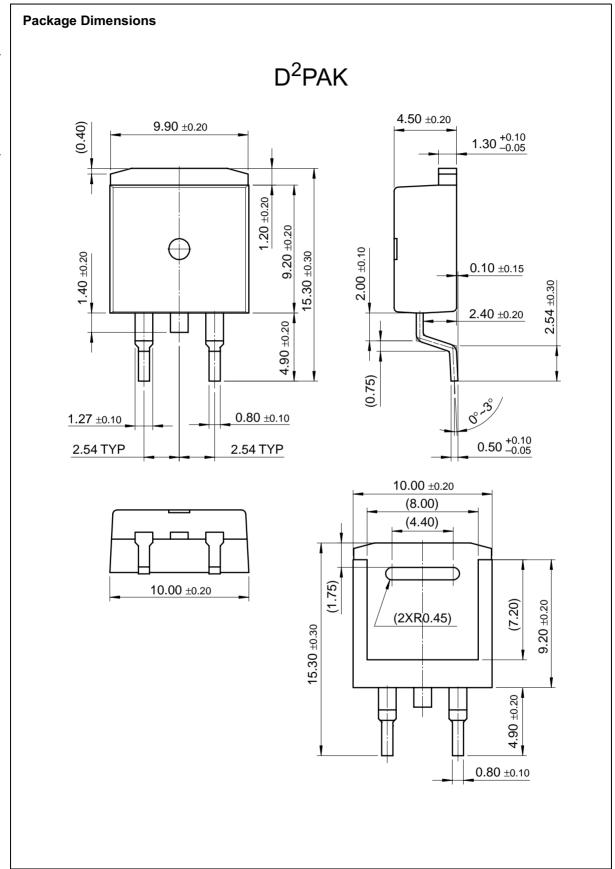




Body Diode Reverse Current

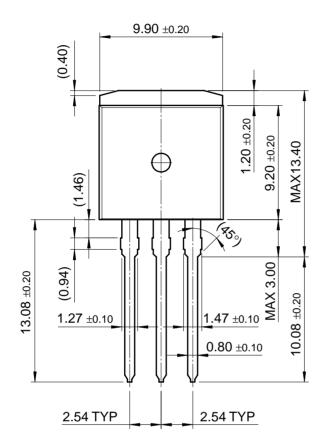


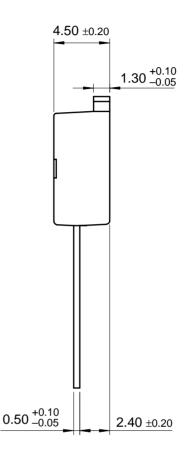
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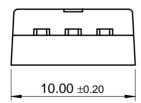




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